

Materials Declaration Form

IPC	1752	Version	2			
Form Type *	Distribute	Tersion.	-			
Sectionals *	Material Info	Subsectionals *	A-D			
	Manufacturing Info		* : Required Field			

Supplier Information								
Company Name *	STMicroelectronics Response Date *		2016-01-22					
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section					
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD Champion					
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section					
Sunnlier Comment	Online Technical Support - STMicroelectry://www.st.com/web/en/support/s							

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement

Supplier Acceptance * true Legal Declaration * Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product								
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date				
2STD1665T4	CQDP*CA04S62	А	SHENZHEN B/E	2016-01-22				
	Amount	UoM	Unit type	ST ECOPACK Grade				
	330.00	mg	Each	ECOPACK2				

Manufacturing information								
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles						
1	260	3						
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	life.augmented				
NAC	Tin (Sn), matte	Copper Alloy		mo.ddgmomod				

Package Designator	Size	Nbr of instances	Shape	
SIP	6.5, 6.1, 2.3	3	GULL WING	
Comment	TO 252 DPAK			

	Query	Response					
· •							
1 - Product(s) meets EU RoHS requireme	nt without any exemptions	false					
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may							
apply)							
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s) true							
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions							
5 - Product(s) is obsolete, no information is available							
6 - Product(s) is unknown, no information is available							
Exemption Id.	Exemption Id. Description						
7a Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)							

QueryList : REACH-17th December 2015								
Query Response								
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH								
CategoryLevel_Name CategoryLevel_Threshold amount in product (mg) Application								

Material Composition Declaration			Mfr Item Name	CQDP*CA04S62								
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	4.530	mg	supplier	die	Silicon (Si)	7440-21-3		4.403	mg	971949	13345
				supplier	metallization	Aluminium (AI)	7429-90-5		0.051	mg	11256	155
				supplier	Passivation	Silicon Oxide	7631-86-9		0.058	mg	12800	176
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.009	mg	1986	27
				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	1324	18
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.003	mg	662	9
				supplier	back side metallization	Arsenic (As)	7440-38-2		0.0001	mg	22	0
Leadframe	Copper & its alloys	164.944	mg	supplier	alloy	Copper (Cu)	7440-50-8		164.152	mg	995198	497430
				supplier	alloy	CopperPosphorous (CuP)	12517-41-8		0.330	mg	2001	1000
				supplier	alloy	Cobalt (Co)	7440-48-4		0.462	mg	2801	1400
Soft solder	Solder	2.162	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.065	mg	955134	6258
				supplier	solder	Silver (Ag)	7440-22-4		0.054	mg	24977	164
				supplier	solder	Tin (Sn)	7440-31-5		0.043	mg	19889	130
Bonding wires	Other inorganic materials	0.147	mg	supplier	wire	Copper (Cu)	7440-50-8		0.147	mg	1000000	445
Encapsulation	Other Organic Materials	157.172	mg	supplier	mold compound	Silica, vitreous	60676-86-0		137.525	mg	874997	416742
				supplier	mold compound	Tetramethyl-biphenyl-diyl-bis oxymethylene-b	EC 413-900-7		6.287	mg	40001	19052
				supplier	mold compound	Epoxy Resin	25068-38-6		4.715	mg	29999	14288
				supplier	mold compound	phenol resin	29690-82-2		7.859	mg	50003	23815
				supplier	mold compound	Carbon black	1333-86-4		0.786	mg	5001	2382
Connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3167